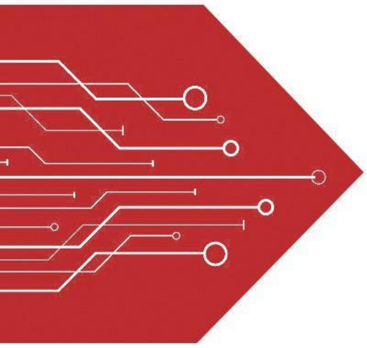
MSKSEMI
SEMICONDUCTOR



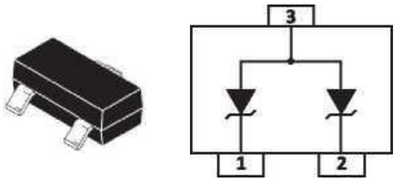
ESD TVS TSS MOV GDT PLED

Product data sheet

www.msksemi.com

FEATURES

350 Watts peak pulse power per Line(tp=8/20^S)
Protects one bidirectional line or two unidirectional lines
Low clamping voltage
RoHS Compliant



SOT-23

APPLICATIONS

Cellular Handsets and Accessories
Portable Electronics
Industrial Controls
Set-Top Box
Instrumentation
Servers, Notebook, and Desktop PC

IECCOMPATIBILITY

IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
IEC61000-4-4 (EFT) 40A (5/50ns)

MAXIMUM RATINGS @25°C UNLESS OTHERWISE SPECIFIED

MAXIMUM RAT INGS @25°c UNLESS OTHERWISE SPECIFIED

PARAMETER	SY M B OL	VALUE	UNIT
Peak Pulse Power (tp=8/20 μ s waveform)	P_{PP}	350	Watts
Operadng Temperature Range	T_J	-55-125	°C
Storage Temperature Range	T_{STG}	-55-150	°C

ELECTRICAL CHARACTERISTICS PER LINE@ 25°C UNLESS OTHERWISE SPECIFIED

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PART NUMBER	MARKING	V RWM (V) Max.	V BR (V) Min.	I_T (mA)	V c @1A Max.	V c		1 R (uA) Max.	C_T (pF) Max.
						Max.	@A		
MSKSM03	M03	3.3	4.0	1	6.5	15.0	25	100	400
MSKSM05	M05	5.0	6.0	1	9.8	16.0	24	10	300
MSKSM08	M08	8.0	8.5	1	13.4	19.0	18	5	250
MSKSM12	M12	12.0	13.3	1	19.0	24.0	13	1	150
MSKSM15	M15	15.0	16.7	1	24.0	28.0	6	1	100
MSKSM24	M24	24.0	26.7	1	43.0	52.0	6	1	90

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

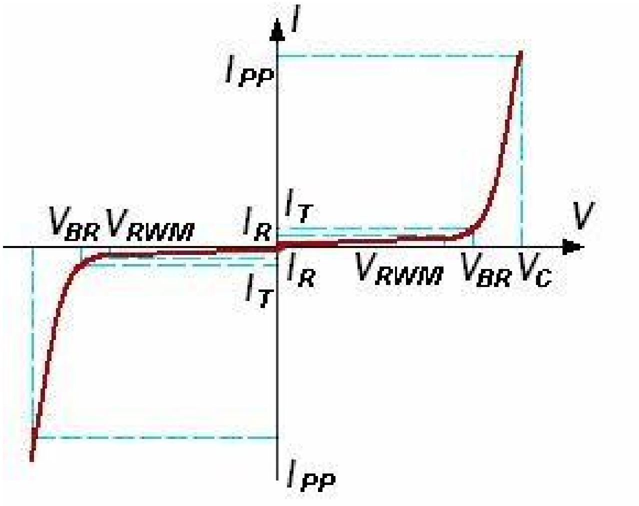


FIG1: Pulse Waveform

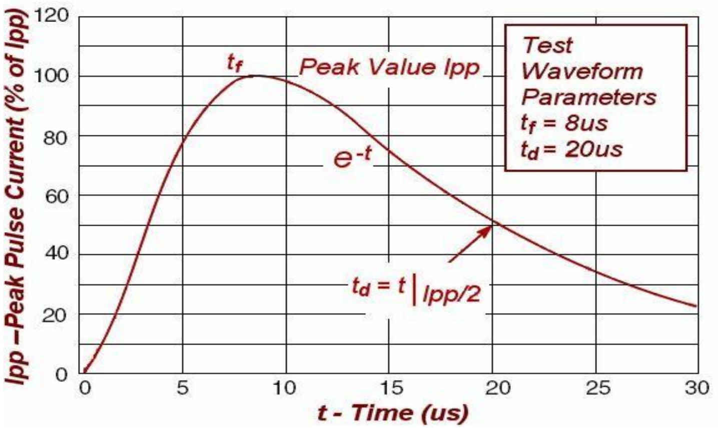
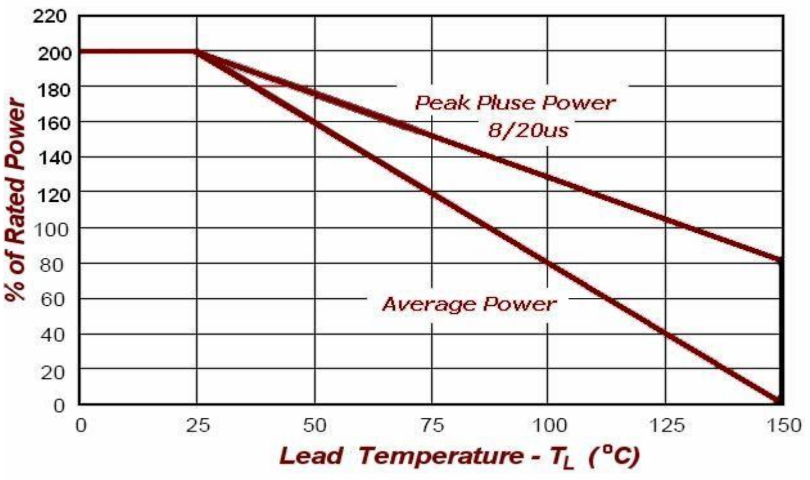
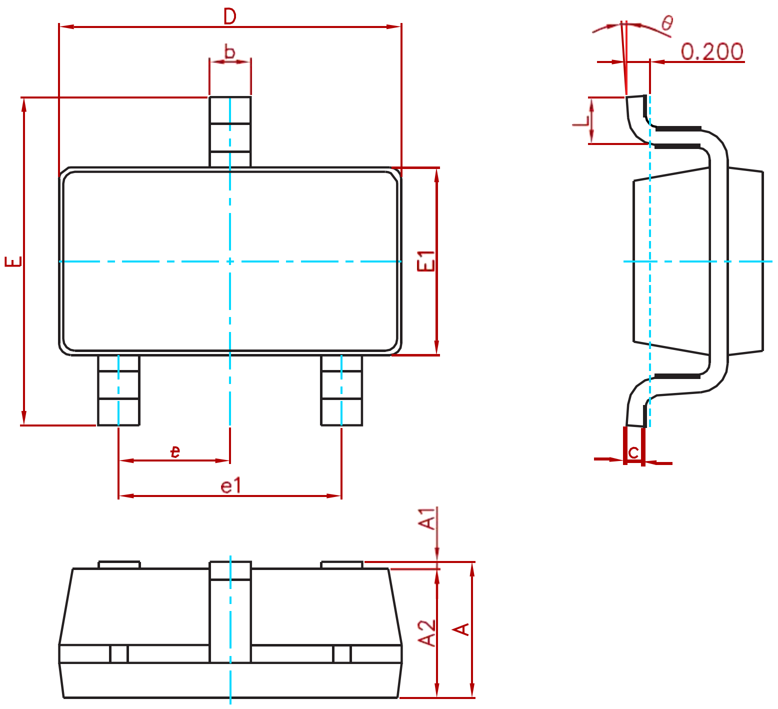


FIG2:Power Derating

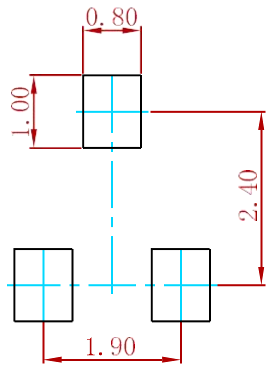


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
0	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MSKSM03-MSKSM24	SOT-23	3000

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